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BGA stencils for Huawei HI Power 0.12mm

Product ID: 22172

Price: **12.00 EUR**

Product weight: **0.01 kg**

Description:

BGA stencils for Huawei HI Power 0.12mm allows reballing of 10 models: HI6555, HI6561, HI6553, HI6421GFC, HI6421A, HI6421B, HI6522, HI6551, HI6523.

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